

TABLE 1 SWITCH CIRCUIT

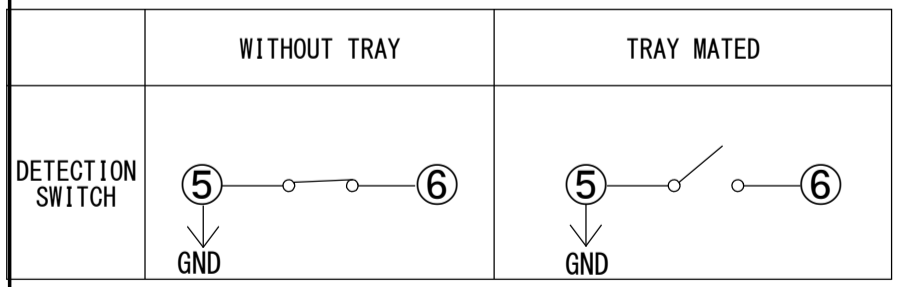


TABLE 3 4FF SIM PIN ASSIGNMENT

C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	Vpp
C7	I/O

TABLE 4 microSD PIN ASSIGNMENT

#1	DAT2
#2	DAT3
#3	CMD
#4	VDD
#5	CLK
#6	VSS
#7	DAT0
#8	DAT1

TABLE 2 FINISH

PART No.	PART NAME	BASE PLATING		TOP PLATING	
		CONTACT AREA	TERMINAL AREA	CONTACT AREA	TERMINAL AREA
①	CONTACT (4FF SIM)	Ni (1~6 μm)	Ni (1~6 μm)	Au (0.3 μm min.)	Au (0.03 μm min.)
②	CONTACT (μSD)	Ni (1~6 μm)	Ni (1~6 μm)	Au (0.3 μm min.)	
④	COVER	-	Ni (0.5~6 μm)	-	
⑤	DETECTION SWITCH1 (DSW1)	-	Ni (1~6 μm)	Au (0.1 μm min.)	
⑥	DETECTION SWITCH2 (DSW2)	-	Ni (1~6 μm)	Au (0.1 μm min.)	

NOTE1. OTHER COMPONENTS CANNOT TOUCH OR REST ON THIS AREA.
 NOTE2. ONLY GND PATTERN AND GND VIA HOLE IN ALLOWED IN THIS AREA.
 NOTE3. NO PATTERN AND VIA HOLE IN THIS AREA.
 NOTE4. DUMMY PAD SHOULD BE ELECTRICALLY ISOLATED. (No connection to GND on something else)
 No solder on this PAD
 NOTES. RECOMMENDED OPEN APERTURE RATIO OF STENCIL MASK : 100% THICKNESS : 0.1mm
 NOTE6. LOT INFORMATION IS SHOWN AS BELOW.
 i.e. 6 X 2 5 1

PRODUCT LINE No. 6 : YEAR (2016)
 PRODUCTION DATE (YMD) 0 : MONTH (1, 2, 3, ..., 9, 0, X, Y)
 28 : DAY
 1 : PRODUCT LINE No. (1, 2, 3, ...)

APPLICABLE PCB DIMENSION (2:1)

符号 No.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
8	EJECT LEVER	1	STAINLESS STEEL	-	
7	EJECT BAR	1	STAINLESS STEEL	-	
6	DETECTION SWITCH2 (DSW2)	1	COPPER ALLOY	Au over Ni	
5	DETECTION SWITCH1 (DSW1, GND)	1	COPPER ALLOY	Au over Ni	
4	COVER	1	STAINLESS STEEL	Au over Ni	
3	HOUSING	1	LCP	-	
2	CONTACT2 (μSD)	8	COPPER ALLOY	Au over Ni	
1	CONTACT1 (4FF SIM)	12	COPPER ALLOY	Au over Ni	

仕様書 (SPECIFICATION)
 JACS-11162*
 JAHL-11162*

第1版 (ORIGINAL DATE)
 25/NOV/2016

尺度 (SCALE)
 5:1

製図 DR. 担当 CHK. K. MIKAWA
 査閲 APPD. K. KUME
 承認 APPD. M. SHIMADA

名称 (TITLE)
 ST19S020VCA

質量 (MASS)

図面番号 (DRAWING NO.)
 SJ117667

版数 (VER.)
 2